CLAIMS

1. A tape for semiconductor processing comprising:

a dicing tape having a base film and a pressure-sensitive adhesive layer;

a metal layer provided on the pressure-sensitive adhesive layer; and

an adhesive layer provided on the metal layer for adhering the metal layer to the back surface of a semiconductor chip,

wherein the surface roughness RzJIS of the metal layer based on the 10-point average roughness is 0.5 μm or more and less than 10.0 μm, wherein the saturation moisture absorption ratio of the adhesive layer is 1.0 vol% or less, and the residual volatile matter content of the adhesive layer is 3.0 wt% or less.

2. The tape for semiconductor processing according to claim 1, wherein the metal layer is a copper foil.

3. The tape for semiconductor processing according to claim 1 or claim 2, wherein the adhesive layer contains (A) an epoxy resin, (B) a curing agent, (C) a phenoxy resin, and (D) a surface-treated inorganic filler, and the content of component (D) is from 40% by weight to 65% by weight with respect to the total amount of components (A) to (D).

4. The tape for semiconductor processing according to any one of claims 1 to 3, wherein the pressure-sensitive adhesive layer contains an acrylic polymer composed of an acrylic acid ester represented by the formula: CH_2=CHCOOR (wherein R

represents an alkyl group having 4 to 8 carbon atoms), a hydroxyl group-containing monomer, and an isocyanate compound having a radical reactive carbon-carbon double bond in the molecule.